

**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

|                      |                                                                                                                     |                                      |
|----------------------|---------------------------------------------------------------------------------------------------------------------|--------------------------------------|
| 1.1 Company          |                                    | STMicroelectronics International N.V |
| 1.2 PCN No.          | ANALOG MEMS SENSORS/26/16063                                                                                        |                                      |
| 1.3 Title of PCN     | ST Manufacturing Reshaping : Analog_EWS ONLY_ AGR to SGP ALL: Qualification of SGP (Singapore) as new EWS Location. |                                      |
| 1.4 Product Category | Please refer to the impacted Product list                                                                           |                                      |
| 1.5 Issue date       | 2026-02-10                                                                                                          |                                      |

**2. PCN Team**

|                                  |                                     |
|----------------------------------|-------------------------------------|
| <b>2.1 Contact supplier</b>      |                                     |
| 2.1.1 Name                       | PIKE EMMA                           |
| 2.1.2 Phone                      | +44 1628896111                      |
| 2.1.3 Email                      | emma.pike@st.com                    |
| <b>2.2 Change responsibility</b> |                                     |
| 2.2.1 Product Manager            | Domenico ARRIGO                     |
| 2.1.2 Marketing Manager          | Elena Maria PERNIGOTTI,Fabio CHELLI |
| 2.1.3 Quality Manager            | Paolo MORETTI                       |

**3. Change**

|                                 |                                 |                            |
|---------------------------------|---------------------------------|----------------------------|
| 3.1 Category                    | 3.2 Type of change              | 3.3 Manufacturing Location |
| Manufacturing reshaping program | Manufacturing reshaping program | New EWS = SGP (Singapore)  |

**4. Description of change**

|                                                                                       |                                                                                                              |                       |
|---------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------|-----------------------|
|                                                                                       | Old                                                                                                          | New                   |
| 4.1 Description                                                                       | EWS = AGR (Italy)                                                                                            | EWS = SGP (Singapore) |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No Impact. The products guarantee the same quality and electrical characteristics as per current production. |                       |

**5. Reason / motivation for change**

|                      |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
|----------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5.1 Motivation       | In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of SGP (Singapore) as EWS Location.<br>Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available. |
| 5.2 Customer Benefit | SERVICE CONTINUITY                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |

**6. Marking of parts / traceability of change**

|                 |                       |
|-----------------|-----------------------|
| 6.1 Description | Internal traceability |
|-----------------|-----------------------|

**7. Timing / schedule**

|                                     |                |
|-------------------------------------|----------------|
| 7.1 Date of qualification results   | 2026-01-17     |
| 7.2 Intended start of delivery      | 2026-04-09     |
| 7.3 Qualification sample available? | Not Applicable |

**8. Qualification / Validation**

|                                                    |             |            |  |
|----------------------------------------------------|-------------|------------|--|
| 8.1 Description                                    |             |            |  |
| 8.2 Qualification report and qualification results | In progress | Issue Date |  |

| 9. Attachments (additional documentations) |  |
|--------------------------------------------|--|
| 16063 Public product.pdf                   |  |

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | L6364Q                  |                          |
|                         | L6364W                  |                          |

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